



TechInsights' 2026 Global Semiconductor Industry Customer Satisfaction Survey

Fourteenth Consecutive Triple Crown Win

EV Group Awarded #1 Global Semiconductor Supplier Awards

- **EV Group, the industry-leading wafer-bonder supplier, earns Global #1 in:**
 - Fab Equipment
 - WFE to Specialty Chip Makers
 - Lithography Equipment
 - Specialty Fab Equipment
- **As well as earning:**
 - Global Semiconductor Supplier Awards – Top 10 Customer Service – Focused Suppliers of Chip Making Equipment
 - Global Semiconductor Supplier Awards – Fab Equipment
 - Global Semiconductor Supplier Awards – WFE to Specialty Chip Makers
- EV Group wins all three awards for the 14th consecutive year
- 24th consecutive year earning an award for Fab Equipment suppliers
- 10th consecutive year earning an award for WFE to Specialty Semiconductor Makers
- Rated #2 among Focused Equipment Suppliers in the 2026 Top 10 rankings with an overall rating of 9.16
- Earns its highest score in Partnering with a 9.4

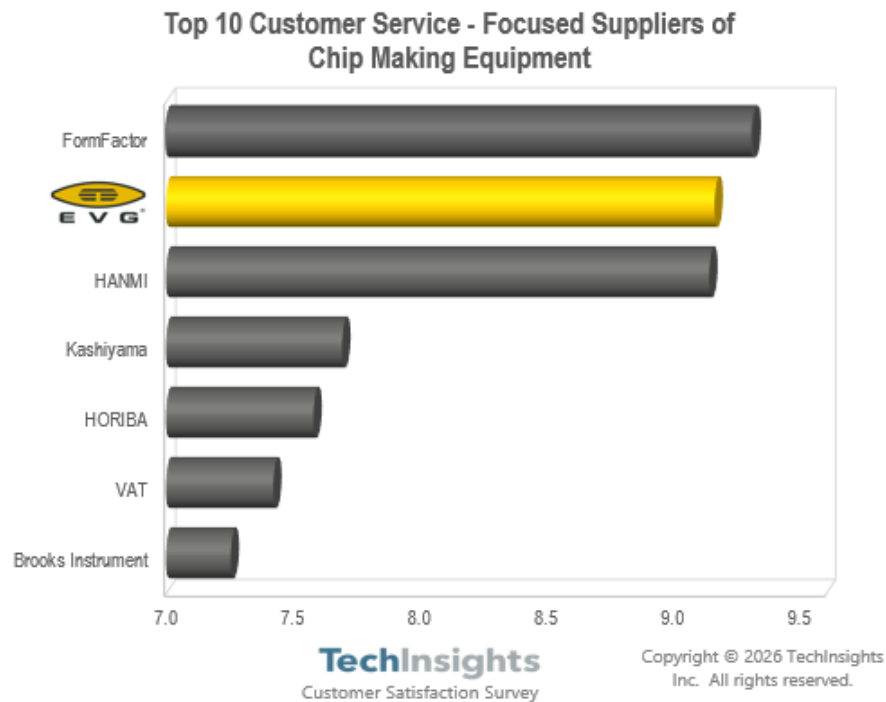


Figure 1 – TechInsights 2026 Global Semiconductor Supplier Awards – Top 10 Focused

How Customers Perceive EV Group

- Increases its ratings in 3 rating categories
 - Spares Support by 20 basis points
 - Recommend Supplier and Trust in Supplier by 10 basis points
- Earns the highest score of all Fab Equipment Suppliers in 12 categories
- Highest-scoring categories (listed highest to lowest):
 - Partnering – 9.4
 - Recommend Supplier – 9.4
 - Trust in Supplier – 9.4
 - Technical Leadership – 9.3
 - Application Support – 9.2
 - Quality of Results – 9.2
 - Product Performance – 9.2
 - Commitment – 9.1
 - Field Engineering Support – 9.1
 - Spares Support – 9.1
 - Support After Sales – 9.0
 - Uptime – 9.0
 - Software – 9.0

– Overall Value – 8.9

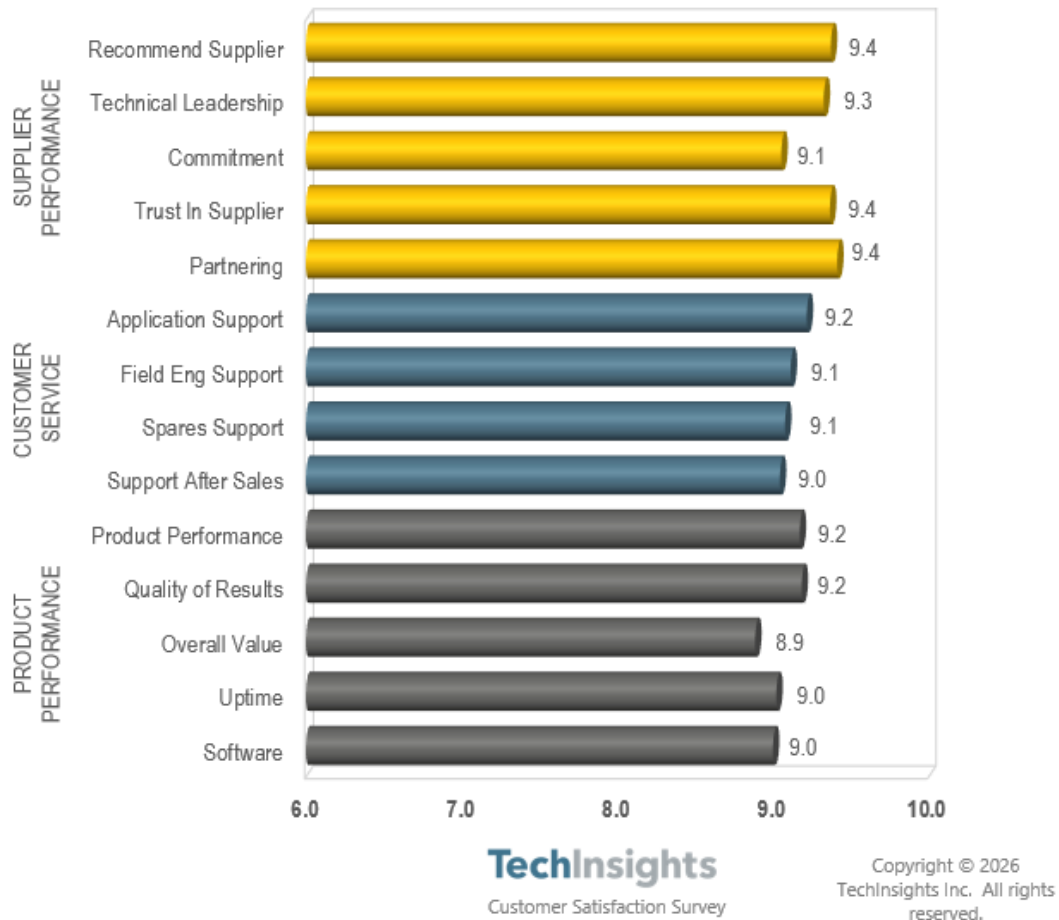


Figure 2 – EV Group 2026 Category Ratings

More Perceptions From Customers

“Worked as partner since 2014, very good track record.”

“Technical leadership and technical support.”

“Excellent service – always endeavoured to support.”

“High reliability for both equipment and personnel.”

“I really like working with both the equipment and the personnel from EV Group.”

“Excellent tools and incomparable support.”

“Very good product, service and solutions. Very good support for demo and process support at EVG facilities.”

“Product quality, quality of service and support.”

“World class wafer bonding tech innovator – they contribute advanced tech not only for 300mm fab but also smaller substrate fabs.”

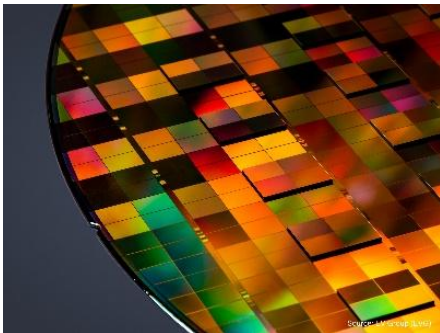
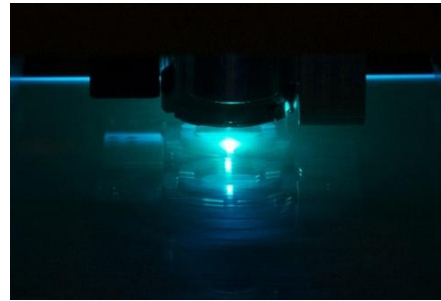
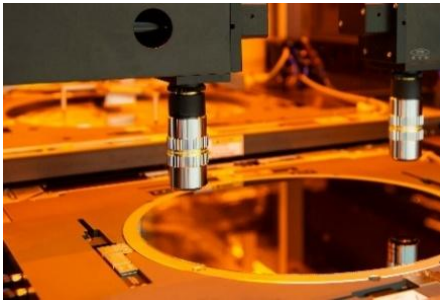
“They have excellent tools and service support.”

“Overall, we are satisfied with EVG’s equipment and technological capabilities, and we look forward to continuing our cooperation in the future.”

“Friendly and quick response; process equipment results reliability.”

EV Group's Approach to Customer Satisfaction

- Introduction of the industry's first true high-throughput/high-resolution digital lithography solution for high-volume-manufacturing (HVM) heterogeneous integration applications
- EVG provides solutions for manufacturing semiconductors, MEMS, compound semiconductors, power devices, and nanotechnology devices
- Process knowledge focus is key to developing core capabilities of wafer bonding, lithography, and metrology
- Strong pre-sales process development support recognized as a differentiator by customers in equipment selection and tool specification
- Global field service and applications engineering network with state-of-the-art cleanrooms in Europe, North America, and Asia serves customers across the world.





Recent Technology Milestone

EV Group continues to push the boundaries of wafer bonding technology. A recent breakthrough collaboration with imec demonstrates the depth of EVG's technical leadership:

Imec and EV Group Demonstrate Wafer-to-Wafer Hybrid Bonding with 200nm Interconnect Pitch and Record High Overlay Accuracy

- Imec and EVG demonstrate highly yielding wafer-to-wafer hybrid bonding technology at 200nm Cu interconnect pad pitch with record high post-bonding alignment accuracy
- Marks a milestone in enabling advanced logic-to-logic and memory-to-logic tier stacking as envisioned in imec's CMOS 2.0 scaling paradigm
- Achieved by co-optimizing all critical elements of imec's wafer-to-wafer hybrid bonding process flow leveraging EVG's most advanced wafer bonding equipment
- Announced at the 2026 IEEE Electronics Components and Technology Conference (ECTC)

Read more: <https://www.evgroup.com/company/news/detail/imec-and-ev-group-demonstrate-wafer-to-wafer-hybrid-bonding-with-200nm-interconnect-pitch-and-record-high-overlay-accuracy>

About EV Group

EV Group (EVG) provides innovative process solutions and expertise that serve leading-edge and future semiconductor designs and chip integration schemes. The company's vision of being first in exploring new techniques and supporting next-

generation applications of micro- and nanofabrication technologies enables customers to successfully commercialize new product ideas. EVG's high-volume-manufacturing-ready products, which include wafer bonding, lithography, thin-wafer processing and metrology equipment, enable advances in semiconductor front-end scaling, 3D integration and advanced packaging, as well as in other electronics and photonics applications.

Founded in 1980, EVG services and supports an elaborate network of global customers and partners worldwide, with more than 1,700 employees worldwide and fully owned subsidiaries in the U.S., Japan, South Korea, China, Taiwan and Singapore.

More information about EVG is available at www.EVGroup.com

About the TechInsights' 2026 Global Semiconductor Industry Customer Satisfaction Survey

TechInsights received feedback from more than 46% of the chip market for this year's survey. The survey spans 2½ months and covers five languages. Worldwide participants were asked to rate equipment suppliers across multiple categories based on three key factors: supplier performance, customer service, and product performance. 1,201 surveys were returned for the 2026 survey year.

The TechInsights annual Customer Satisfaction Survey is the only publicly available opportunity since 1988 for customers to provide feedback to suppliers of semiconductor equipment and subsystems. The awards provide special recognition to suppliers that are rated highest by their customers.

Top 10 Customer Service awards recognize each chip making equipment supplier as a whole, regardless of product type:

- Fab, Test, Assembly, and WFE Subsystems equipment ratings are grouped together for an overall rating for each supplier

- Each supplier is then listed in one of two categories based on a three-year average of total revenues: Large or Focused

Global Semiconductor Supplier Awards recognize the more detailed markets:

- Fab Equipment, Assembly/Test Equipment, WFE to Foundation Chip Makers, WFE to Specialty Chip Makers, Assembly Subsystems, Test Subsystems, and WFE Subsystems

Global #1 awards place special distinction on suppliers that achieve the highest rating in any survey category:

- 10 BEST and THE BEST
- Specialized areas such as: CMP, Deposition, Etch & Clean, Implant, Lithography, Process Diagnostics, Specialty Fab, Assembly Subsystems, Test Subsystems, and WFE Subsystems

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